

ABSTRACT OF THE DISCLOSURE

Molding Apparatus

Molding apparatus (200) is provided for simultaneously molding a molding
 5 material around a number of separate substrates, each substrate having a
 semiconductor chip mounted thereon. The apparatus includes a mold holder
 (113a, 113b, 114, 103) having a first holding section for holding a first mold half
 (119) and a second holding section for holding a second mold half (120). The
 first and second holding sections have a common support surface (135), the
 10 support surface (135) including a first movable member (104a) in the first
 holding section and a second movable member (104b) in the second holding
 section. The first and second movable members (104a, 104b) are movable
 between a first position in which they protrude out of the support surface (135)
 and a second position in which the protrusion from the support surface (135) is
 15 less than in the first position. A first drive mechanism (100, 110) is coupled to
 the first movable member (104a) and a second drive mechanism (100, 110) is
 coupled to the second movable member (104b). The first and second drive
 mechanisms (100, 110) are adapted to be independently actuated to move the
 first and second movable members (104a, 104b) between the first and second
 20 positions.